



Material Content Data Sheet



Sales Product Name		ICE1HS01G		Issued		27. May 2015		
MA#		MA001051864						
Package		PG-DSO-8-41		Weight*		81.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.020	3.72	3.72	37218	37218
leadframe	inorganic material	phosphorus	7723-14-0	0.008	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.673	0.83		8294	
wire	non noble metal	copper	7440-50-8	27.330	33.68	34.56	336780	345593
	noble metal	gold	7440-57-5	0.116	0.14	0.14	1432	1432
	encapsulation	organic material	carbon black	1333-86-4	0.143	0.18		1758
plastics	plastics	epoxy resin	-	4.613	5.68		56843	
		silicondioxide	60676-86-0	42.800	52.75	58.61	527408	586009
leadfinish	non noble metal	tin	7440-31-5	0.814	1.00	1.00	10029	10029
plating	noble metal	silver	7440-22-4	0.090	0.11	0.11	1104	1104
glue	plastics	acrylic resin	-	0.302	0.37		3723	
		noble metal	silver	7440-22-4	1.209	1.49	1.86	14892
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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